

Paul Paret

List of Publications by Year in descending order

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Version: 2024-02-01

10
papers

57
citations

2258059

3
h-index

2272923

4
g-index

10
all docs

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docs citations

10
times ranked

62
citing authors

#	ARTICLE	IF	CITATIONS
1	Transient Liquid Phase Bonding of AlN to AlSiC for Durable Power Electronic Packages. <i>Advanced Engineering Materials</i> , 2018, 20, 1800039.	3.5	16
2	Reliability of Bonded Interfaces for Automotive Power Electronics. , 2013, , .		9
3	Liquid-Cooled Aluminum Silicon Carbide Heat Sinks for Reliable Power Electronics Packages. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2019, 141, .	1.8	9
4	Packaging of an 8-kV Silicon Carbide Diode Module with Double-Side Cooling and Sintered-Silver Joints. , 2021, , .		9
5	Reliability and Lifetime Prediction Model of Sintered Silver Under High-Temperature Cycling. <i>IEEE Journal of Emerging and Selected Topics in Power Electronics</i> , 2022, 10, 5181-5191.	5.4	7
6	Mechanical Characterization Study of Sintered Silver Pastes Bonded in a Double-Lap Configuration. , 2018, , .		2
7	Electrothermal Modeling and Analysis of Gallium Oxide Power Switching Devices. , 2019, , .		2
8	Parametric Design Study of a Power Electronics Package for Improving Solder Joint Reliability. , 2020, , .		1
9	Thermal and Mechanical Design of a High-Voltage Power Electronics Package. , 2021, , .		1
10	Thermomechanical Modeling of Sintered Silver – A Fracture Mechanics-Based Approach. <i>Additional Conferences (Device Packaging HiTEC HiTEN & CICMT)</i> , 2017, 2017, 1-15.	0.2	1